

100V Single P-Channel Enhancement-Mode MOSFET

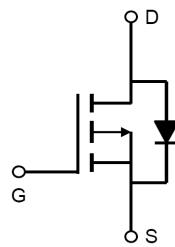
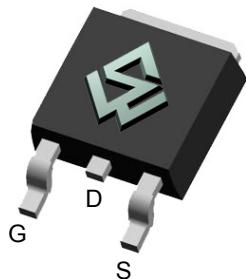
General Description

- Low gate charge.
- Uses advanced trench process technology.
- Use in PWM applications

Product Summary

- | | |
|--------------------------------|---------|
| • BV_{DSS} | -100V |
| • $R_{DS(on)}$ @ $VGS = -10V$ | < 220mΩ |
| • $R_{DS(on)}$ @ $VGS = -4.5V$ | < 255mΩ |

TO-252 D-PAK



Absolute Maximum Ratings ($T_A = 25^\circ C$ unless otherwise noted)

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	-100	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current ($T_A=25^\circ C$)	I_D	-15	A
Drain Current ($T_A=75^\circ C$)		-8	A
Pulsed Drain Current ^a	I_{DM}	-30	A
Power Dissipation ^b ($T_C=25^\circ C$)	P_D	10	W
Power Dissipation ^b ($T_A=25^\circ C$)		2.5	W
Junction and Storage Temperature Range	T_J, T_{STG}	-55 ~ +150	°C

Thermal Characteristics

Parameter	Symbol	Maximum	Units
Junction-to-Ambient ^a ($t \leq 10s$)	$R_{\theta JA}$	25	°C/W
Junction-to-Ambient ^{a,d} (Steady-State)		50	°C/W
Junction-to-Lead (Steady-State)	$R_{\theta JL}$	5	°C/W

Electrical Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise noted)						
Symbol	Parameter	Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}} = 0\text{V}$, $I_D = -250\mu\text{A}$	-100			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}} = -100\text{V}$, $V_{\text{GS}} = 0\text{V}$			-1	μA
I_{GSS}	Gate-Body Leakage Current	$V_{\text{GS}} = \pm 20\text{V}$, $V_{\text{DS}} = 0\text{V}$			± 100	nA
On Characteristics						
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{DS}} = V_{\text{GS}}$, $I_D = -250\mu\text{A}$	-2		-4	V
$R_{\text{DS(ON)}}$	Drain-Source On-State Resistance	$V_{\text{GS}} = -10\text{V}$, $I_D = -7.8\text{A}$		180	220	$\text{m}\Omega$
		$V_{\text{GS}} = -4.5\text{V}$, $I_D = -6\text{A}$		210	255	$\text{m}\Omega$
g_{FS}	Forward Transconductance	$V_{\text{DS}} = -10\text{V}$, $I_D = -7.8\text{A}$		20		S
Drain-Source Diode Characteristics						
V_{SD}	Diode Forward Voltage	$V_{\text{GS}} = 0\text{V}$, $I_S = -10\text{A}$			-1.3	V
I_S	Maximum Body-Diode Continuous Current				-10	A
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{\text{DS}} = -30\text{V}$, $V_{\text{GS}} = 0\text{V}$ $f = 1.0\text{MHz}$		1096		pF
C_{oss}	Output Capacitance			72		pF
C_{rss}	Reverse Transfer Capacitance			43		pF
Switching Characteristics						
Q_g	Total Gate Charge	$V_{\text{DS}} = -50\text{V}$, $I_D = -7.8\text{A}$ $V_{\text{GS}} = -10\text{V}$		20.9		nC
Q_{gs}	Gate-Source Charge			4.5		nC
Q_{gd}	Gate-Drain Charge			5.3		nC
$t_{\text{D(ON)}}$	Turn-On Delay Time	$V_{\text{DD}} = -30\text{V}$, $I_D = -1\text{A}$ $V_{\text{GS}} = -10\text{V}$ $R_{\text{GEN}} = -3 \text{ ohm}$		12		ns
t_r	Turn-On Rise Time			11		ns
$t_{\text{D(OFF)}}$	Turn-Off Delay Time			56		ns
t_f	Turn-Off Fall Time			32		ns

- a. Repetitive rating, Pulse width limited by junction temperature $T_{J(\text{MAX})}=150^\circ\text{C}$. Ratings are based on low frequency and duty cycles to keep initial $T_J=25^\circ\text{C}$
- b. The power dissipation P_D is based on $T_{J(\text{MAX})}=150^\circ\text{C}$, using $\leq 10\text{s}$ junction-to-ambient thermal resistance.
- c. The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$. The value in any given application depends on the user's specific board design.
- d. The $R_{\theta JA}$ is the sum of the thermal impedance from junction to lead $R_{\theta JL}$ and lead to ambient.

Typical Characteristics

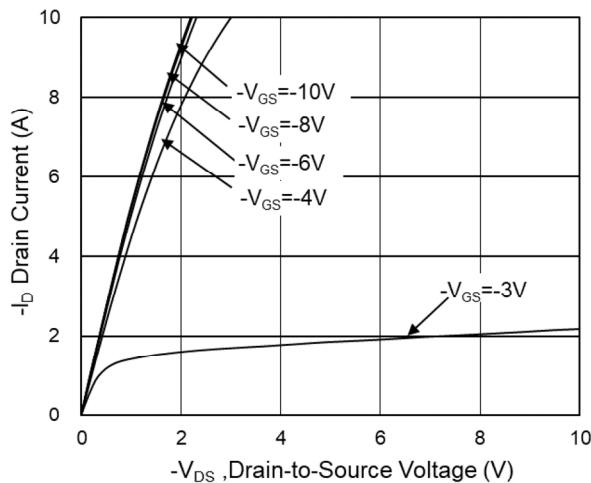


Fig.1 Typical Output Characteristics

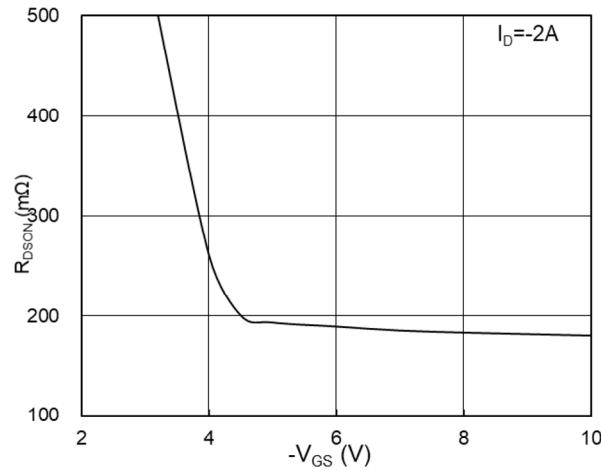


Fig.2 On-Resistance vs G-S Voltage

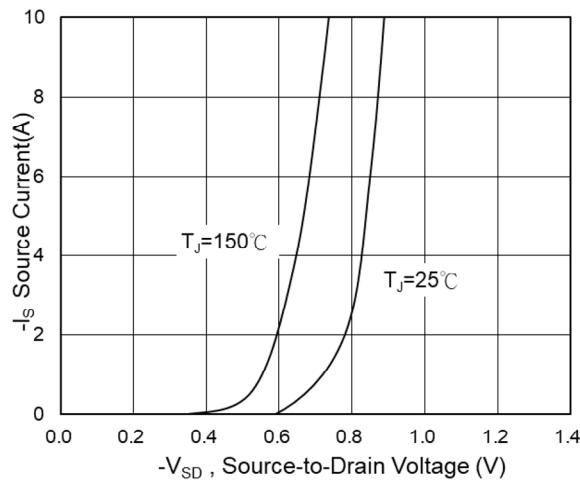


Fig.3 Source Drain Forward Characteristics

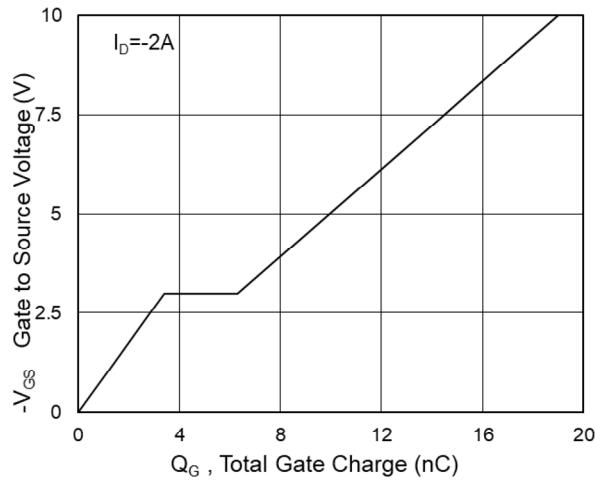


Fig.4 Gate-Charge Characteristics

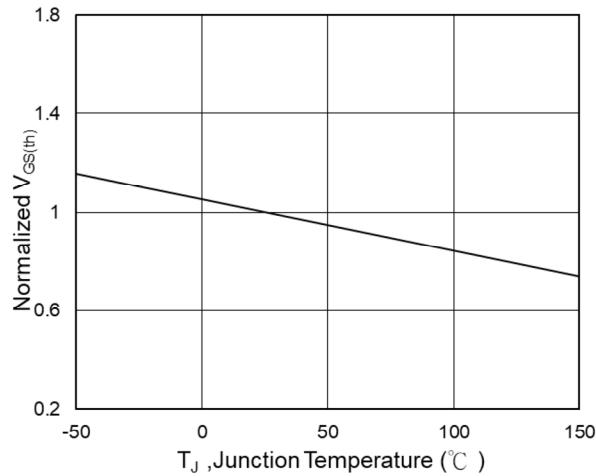


Fig.5 Normalized $V_{GS(th)}$ vs T_J

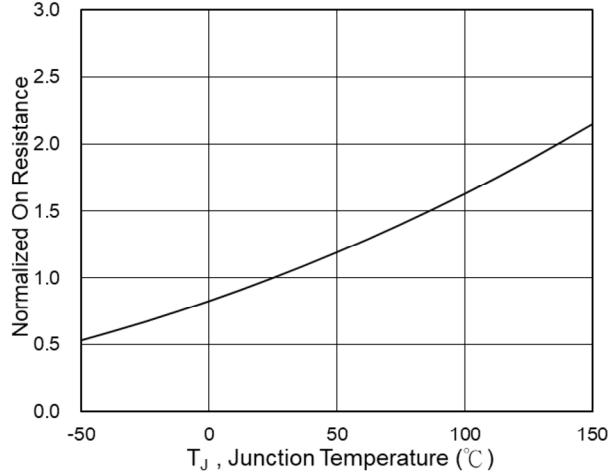
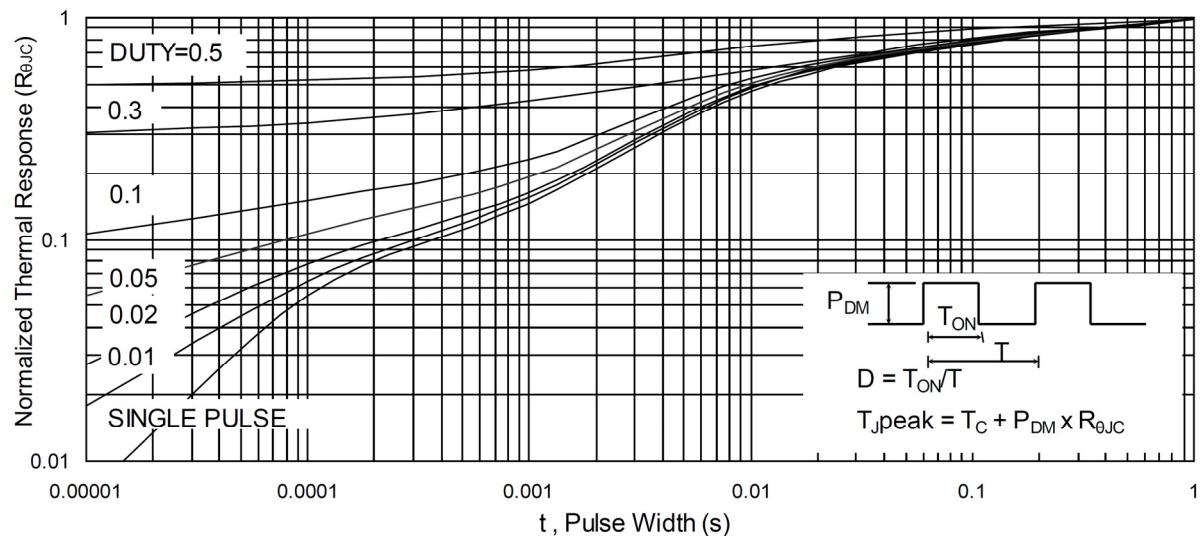
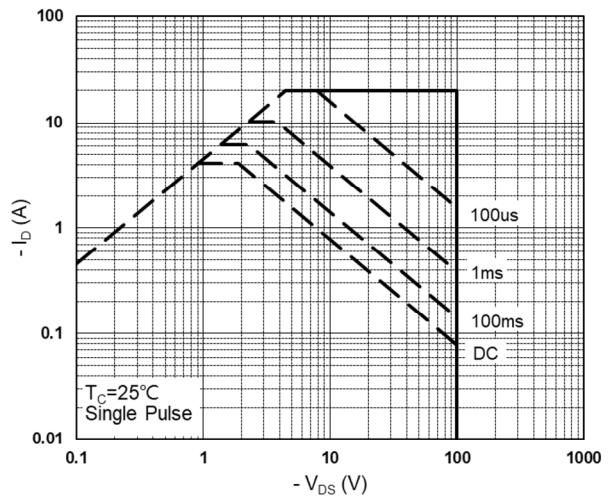
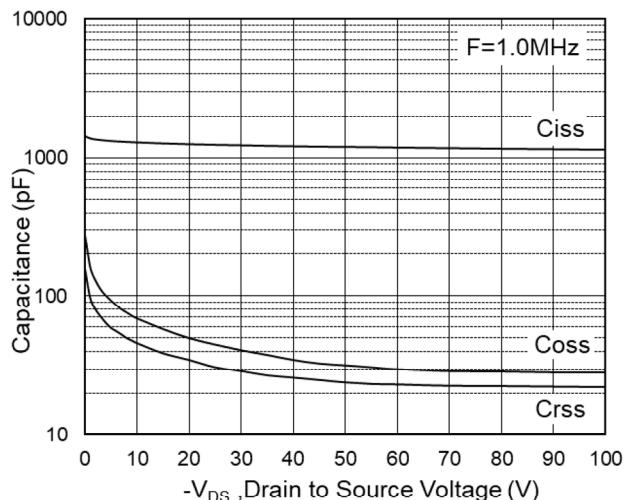
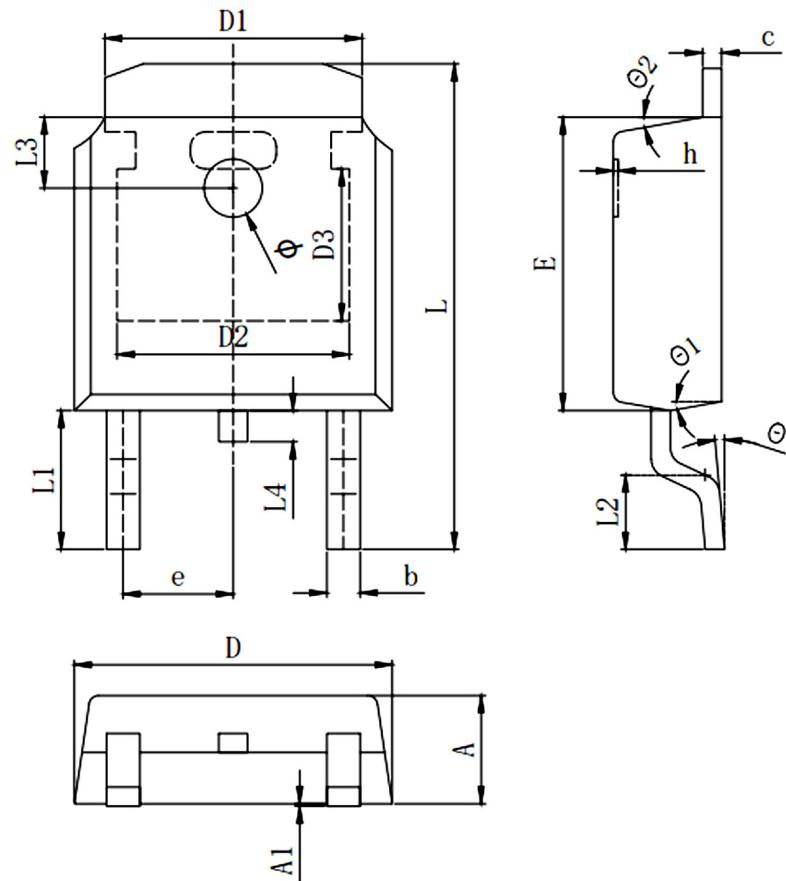


Fig.6 Normalized $R_{DS(on)}$ vs T_J

Typical Characteristics



TO-252 D-PAK Package


Symbols	Millimeters		
	MIN.	Mom.	MAX.
A	2.200	2.300	2.400
A1	0.000		0.127
b	0.640	0.690	0.740
c(电镀后)	0.460	0.520	0.580
D	6.500	6.600	6.700
D1	5.334 REF		
D2	4.826 REF		
D3	3.166REF		
E	6.000	6.100	6.200
e	2.286 TYP		
h	0.000	0.100	0.200
L	9.900	10.100	10.300
L1	2.888 REF		
L2	1.400	1.550	1.700
L3	1.600 REF		
L4	0.600	0.800	1.000
Φ	1.100	1.200	1.300
θ	0°		8°
θ1	9° TYP		
θ2	9° TYP		

单击下面可查看定价，库存，交付和生命周期等信息

>>[SiliconWisdom\(矽睿半导体\)](#)